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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	20000
Total RAM Bits	405504
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp20e-3f256i

Architecture Overview

The LatticeXP architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR) as shown in Figure 2-1.

On the left and right sides of the PFU array, there are Non-volatile Memory Blocks. In configuration mode this non-volatile memory is programmed via the IEEE 1149.1 TAP port or the sysCONFIG™ peripheral port. On power up, the configuration data is transferred from the Non-volatile Memory Blocks to the configuration SRAM. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. This transfer of data from non-volatile memory to configuration SRAM via wide busses happens in microseconds, providing an “instant-on” capability that allows easy interfacing in many applications.

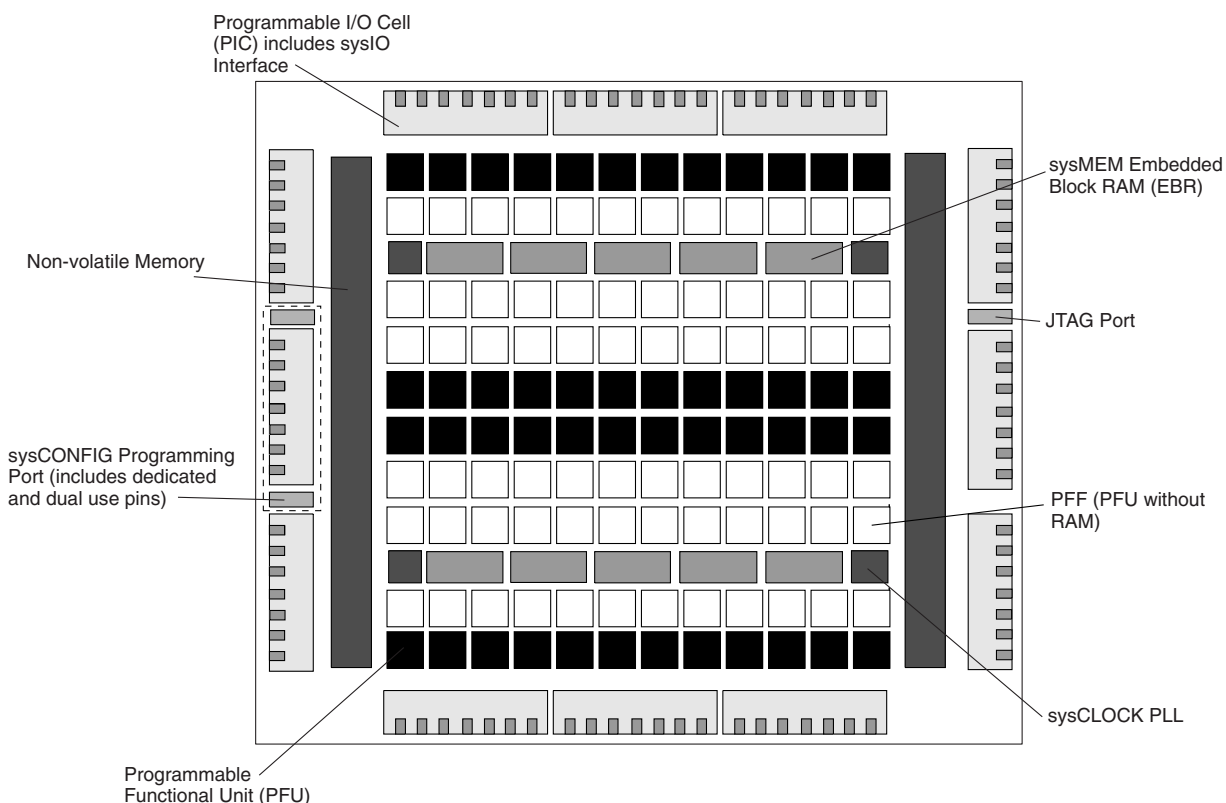
There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional unit without RAM/ROM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM and register functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row. The PFU blocks are used on the outside rows. The rest of the core consists of rows of PFF blocks interspersed with rows of PFU blocks. For every three rows of PFF blocks there is a row of PFU blocks.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysIO interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM or ROM.

The PFU, PFF, PIC and EBR Blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

At the end of the rows containing the sysMEM Blocks are the sysCLOCK Phase Locked Loop (PLL) Blocks. These PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeXP architecture provides up to four PLLs per device.

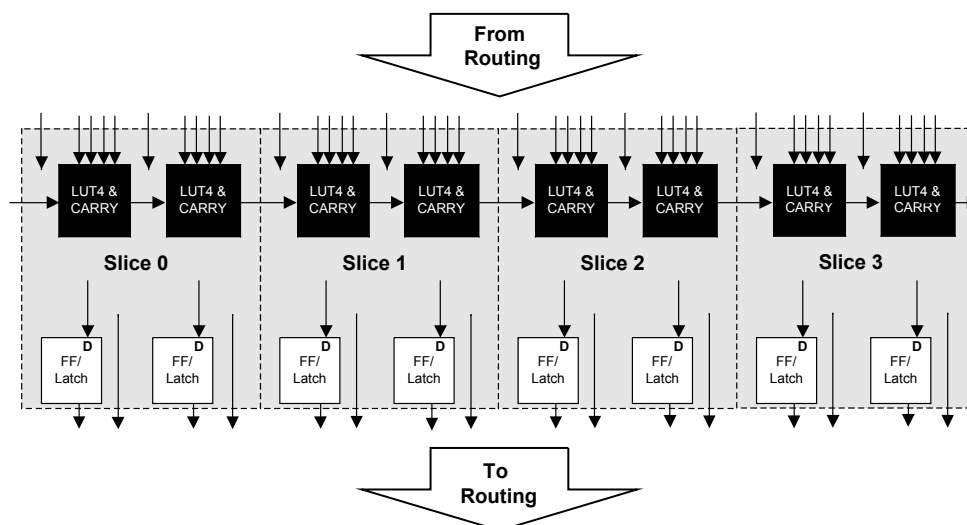
Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG port which allows for serial or parallel device configuration. The LatticeXP devices are available for operation from 3.3V, 2.5V, 1.8V and 1.2V power supplies, providing easy integration into the overall system.

Figure 2-1. LatticeXP Top Level Block Diagram

PFU and PFF Blocks

The core of the LatticeXP devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of the data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram

Slice

Each slice contains two LUT4 lookup tables feeding two registers (programmed to be in FF or Latch mode), and some associated logic that allows the LUTs to be combined to perform functions such as LUT5, LUT6, LUT7 and LUT8. There is control logic to perform set/reset functions (programmable as synchronous/asynchronous), clock select, chip-select and wider RAM/ROM functions. Figure 2-3 shows an overview of the internal logic of the slice. The registers in the slice can be configured for positive/negative and edge/level clocks.

There are 14 input signals: 13 signals from routing and one from the carry-chain (from adjacent slice or PFU). There are 7 outputs: 6 to routing and one to carry-chain (to adjacent PFU). Table 2-1 lists the signals associated with each slice.

Figure 2-3. Slice Diagram

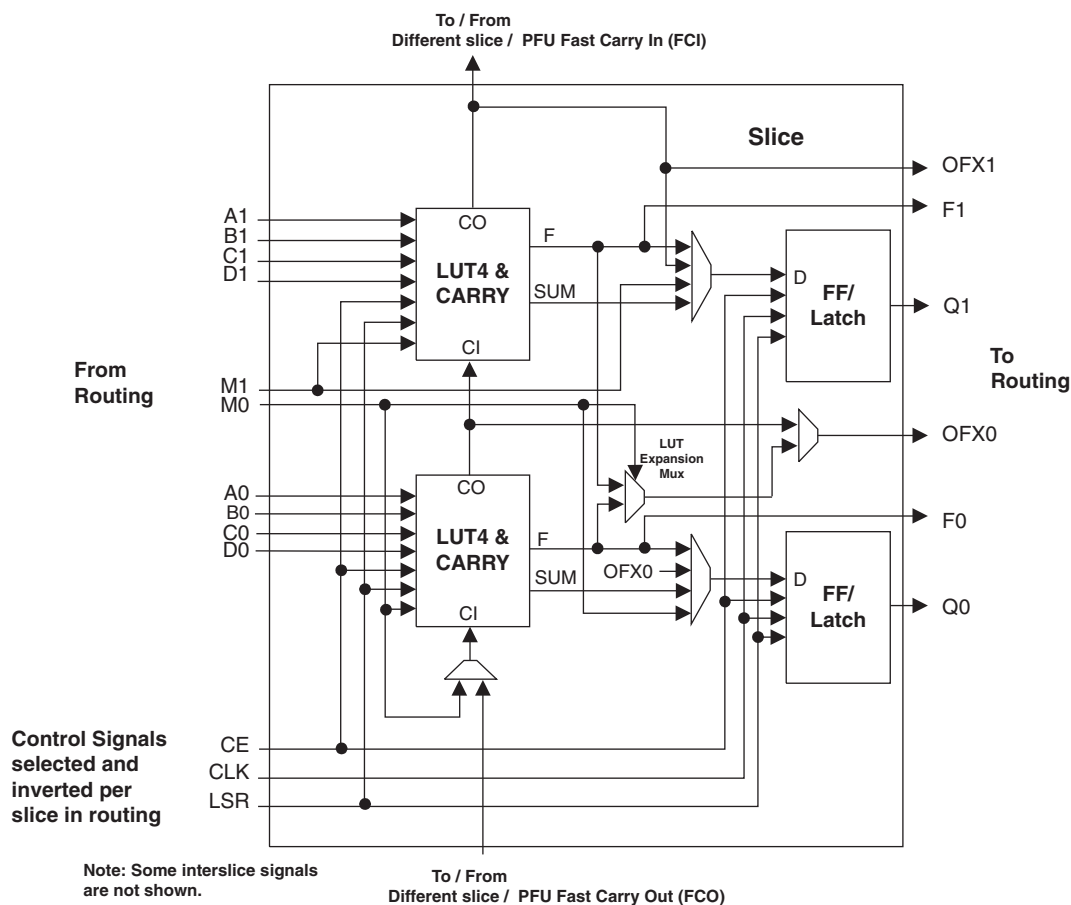


Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM ¹	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Routing

There are many resources provided in the LatticeXP devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal, vertical and diagonal directions. The x2 and x6 resources are buffered allowing both short and long connections routing between PFUs.

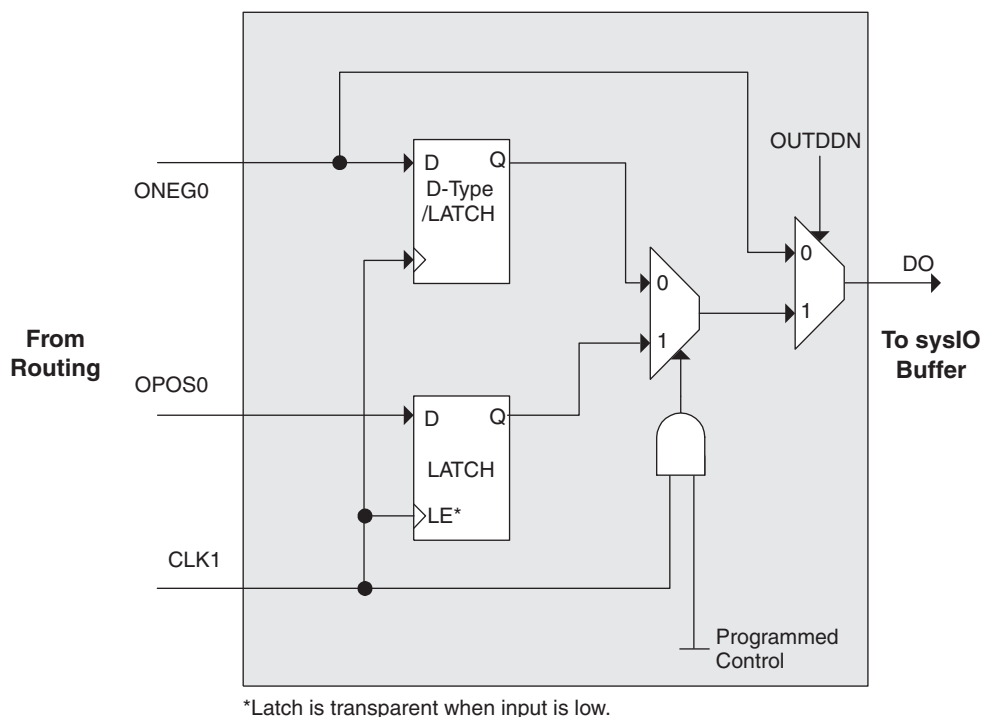
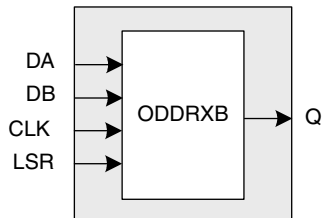
The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock Distribution Network

The clock inputs are selected from external I/O, the sysCLOCK™ PLLs or routing. These clock inputs are fed through the chip via a clock distribution system.

Primary Clock Sources

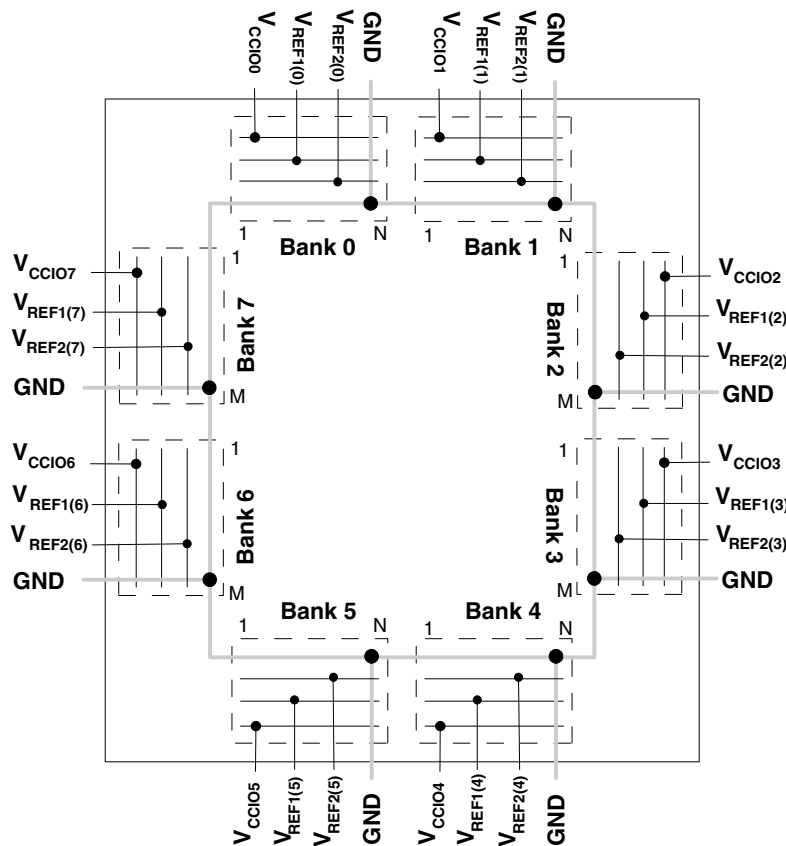
LatticeXP devices derive clocks from three primary sources: PLL outputs, dedicated clock inputs and routing. LatticeXP devices have two to four sysCLOCK PLLs, located on the left and right sides of the device. There are four dedicated clock inputs, one on each side of the device. Figure 2-5 shows the 20 primary clock sources.

Figure 2-23. Output Register Block**Figure 2-24. ODDRXB Primitive****Tristate Register Block**

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-28. LatticeXP Banks



Note: N and M are the maximum number of I/Os per bank.

LatticeXP devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pair (Single-Ended Outputs Only)**

The sysIO buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

Only the I/Os on the top and bottom banks have PCI clamps. Note that the PCI clamp is enabled after V_{CC} , V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysIO Buffer Pair (Differential and Single-Ended Outputs)**

The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Select I/Os in the left and right banks have LVDS differential output drivers. Refer to the Logic Signal Connections tables for more information.

Table 2-9. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static I _{cc}	Typical <100mA	0	Typical <100uA
I/O Leakage	<10μA	<1mA	<10μA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	Off	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up typically in the order of 10μA along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to V_{CC} is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically the device enters Sleep Mode several hundred ns after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet show a detailed timing diagram.

Configuration and Testing

The following section describes the configuration and testing features of the LatticeXP family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All LatticeXP devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port has its own supply voltage V_{CCJ} and can operate with LVCMOS3.3, 2.5, 1.8, 1.5 and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All LatticeXP devices contain two possible ports that can be used for device configuration and programming. The test access port (TAP), which supports serial configuration, and the sysCONFIG port that supports both byte-wide and serial configuration.

The non-volatile memory in the LatticeXP can be configured in three different modes:

- In sysCONFIG mode via the sysCONFIG port. Note this can also be done in background mode.
- In 1532 mode via the 1149.1 port.
- In background mode via the 1149.1 port. This allows the device to be operated while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- In 1532 mode via the 1149.1 port SRAM direct configuration.
- In sysCONFIG mode via the sysCONFIG port SRAM direct configuration.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2 ("C" Version)	-0.3	0.42	0.78	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2 ("E" Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
SSTL2 class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
SSTL18 class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
HSTL15 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL15 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8
HSTL18 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	9.6	-9.6
HSTL18 class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL18 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed $n * 8\text{mA}$. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

Derating Logic Timing

Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

LatticeXP Internal Timing Parameters¹

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
PFU/PFF Logic Mode Timing								
t _{LUT4_PFU}	LUT4 Delay (A to D Inputs to F Output)	—	0.28	—	0.34	—	0.40	ns
t _{LUT6_PFU}	LUT6 Delay (A to D Inputs to OFX Output)	—	0.44	—	0.53	—	0.63	ns
t _{LSR_PFU}	Set/Reset to Output of PFU	—	0.90	—	1.08	—	1.29	ns
t _{SUM_PFU}	Clock to Mux (M0,M1) Input Setup Time	0.13	—	0.15	—	0.19	—	ns
t _{HM_PFU}	Clock to Mux (M0,M1) Input Hold Time	-0.04	—	-0.03	—	-0.03	—	ns
t _{SUD_PFU}	Clock to D Input Setup Time	0.13	—	0.16	—	0.19	—	ns
t _{HD_PFU}	Clock to D Input Hold Time	-0.03	—	-0.02	—	-0.02	—	ns
t _{CK2Q_PFU}	Clock to Q Delay, D-type Register Configuration	—	0.40	—	0.48	—	0.58	ns
t _{LE2Q_PFU}	Clock to Q Delay Latch Configuration	—	0.53	—	0.64	—	0.76	ns
t _{LD2Q_PFU}	D to Q Throughput Delay when Latch is Enabled	—	0.55	—	0.66	—	0.79	ns
PFU Dual Port Memory Mode Timing								
t _{CORAM_PFU}	Clock to Output	—	0.40	—	0.48	—	0.58	ns
t _{SUDATA_PFU}	Data Setup Time	-0.18	—	-0.14	—	-0.11	—	ns
t _{HDATA_PFU}	Data Hold Time	0.28	—	0.34	—	0.40	—	ns
t _{SUADDR_PFU}	Address Setup Time	-0.46	—	-0.37	—	-0.30	—	ns
t _{HADDR_PFU}	Address Hold Time	0.71	—	0.85	—	1.02	—	ns
t _{SUWREN_PFU}	Write/Read Enable Setup Time	-0.22	—	-0.17	—	-0.14	—	ns
t _{HWREN_PFU}	Write/Read Enable Hold Time	0.33	—	0.40	—	0.48	—	ns
PIC Timing								
PIO Input/Output Buffer Timing								
t _{IN_PIO}	Input Buffer Delay	—	0.62	—	0.72	—	0.85	ns
t _{OUT_PIO}	Output Buffer Delay	—	2.12	—	2.54	—	3.05	ns
IOLOGIC Input/Output Timing								
t _{SUI_PIO}	Input Register Setup Time (Data Before Clock)	1.35	—	1.83	—	2.37	—	ns
t _{HI_PIO}	Input Register Hold Time (Data After Clock)	0.05	—	0.05	—	0.05	—	ns
t _{COO_PIO}	Output Register Clock to Output Delay	—	0.36	—	0.44	—	0.52	ns
t _{SUCE_PIO}	Input Register Clock Enable Setup Time	-0.09	—	-0.07	—	-0.06	—	ns
t _{HCE_PIO}	Input Register Clock Enable Hold Time	0.13	—	0.16	—	0.19	—	ns
t _{SULSR_PIO}	Set/Reset Setup Time	0.19	—	0.23	—	0.28	—	ns
t _{HLSR_PIO}	Set/Reset Hold Time	-0.14	—	-0.11	—	-0.09	—	ns
EBR Timing								
t _{CO_EBR}	Clock to Output from Address or Data	—	4.01	—	4.81	—	5.78	ns
t _{COO_EBR}	Clock to Output from EBR Output Register	—	0.81	—	0.97	—	1.17	ns
t _{SUDATA_EBR}	Setup Data to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t _{HDATA_EBR}	Hold Data to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t _{SUADDR_EBR}	Setup Address to EBR Memory	-0.26	—	-0.21	—	-0.17	—	ns
t _{HADDR_EBR}	Hold Address to EBR Memory	0.41	—	0.49	—	0.59	—	ns
t _{SUWREN_EBR}	Setup Write/Read Enable to EBR Memory	-0.17	—	-0.13	—	-0.11	—	ns
t _{HWREN_EBR}	Hold Write/Read Enable to EBR Memory	0.26	—	0.31	—	0.37	—	ns
t _{SUCE_EBR}	Clock Enable Setup Time to EBR Output Register	0.19	—	0.23	—	0.28	—	ns
t _{HCE_EBR}	Clock Enable Hold Time to EBR Output Register	-0.13	—	-0.10	—	-0.08	—	ns

LatticeXP Family Timing Adders¹ (Continued)

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
HSTL15_I	HSTL_15 class I	0.2	0.2	0.2	ns
HSTL15_III	HSTL_15 class III	0.2	0.2	0.2	ns
HSTL15D_I	Differential HSTL 15 class I	0.2	0.2	0.2	ns
HSTL15D_III	Differential HSTL 15 class III	0.2	0.2	0.2	ns
SSTL33_I	SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33_II	SSTL_3 class II	0.3	0.3	0.3	ns
SSTL33D_I	Differential SSTL_3 class I	0.1	0.1	0.1	ns
SSTL33D_II	Differential SSTL_3 class II	0.3	0.3	0.3	ns
SSTL25_I	SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25_II	SSTL_2 class II	0.3	0.3	0.3	ns
SSTL25D_I	Differential SSTL_2 class I	-0.1	-0.1	-0.1	ns
SSTL25D_II	Differential SSTL_2 class II	0.3	0.3	0.3	ns
SSTL18_I	SSTL_1.8 class I	0.1	0.1	0.1	ns
SSTL18D_I	Differential SSTL_1.8 class I	0.1	0.1	0.1	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.8	0.8	0.8	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.5	0.5	0.5	ns
LVTTTL33_12mA	LVTTTL 12mA drive	0.3	0.3	0.3	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.4	0.4	0.4	ns
LVTTTL33_20mA	LVTTTL 20mA drive	0.3	0.3	0.3	ns
LVC MOS33_2mA	LVC MOS 3.3 2mA drive	0.8	0.8	0.8	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.8	0.8	0.8	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.5	0.5	0.5	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	0.3	0.3	0.3	ns
LVC MOS33_16mA	LVC MOS 3.3 16mA drive	0.4	0.4	0.4	ns
LVC MOS33_20mA	LVC MOS 3.3 20mA drive	0.3	0.3	0.3	ns
LVC MOS25_2mA	LVC MOS 2.5 2mA drive	0.7	0.7	0.7	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.7	0.7	0.7	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.4	0.4	0.4	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.0	0.0	0.0	ns
LVC MOS25_16mA	LVC MOS 2.5 16mA drive	0.2	0.2	0.2	ns
LVC MOS25_20mA	LVC MOS 2.5 20mA drive	0.4	0.4	0.4	ns
LVC MOS18_2mA	LVC MOS 1.8 2mA drive	0.6	0.6	0.6	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.6	0.6	0.6	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.4	0.4	0.4	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	0.2	0.2	0.2	ns
LVC MOS18_16mA	LVC MOS 1.8 16mA drive	0.2	0.2	0.2	ns
LVC MOS15_2mA	LVC MOS 1.5 2mA drive	0.6	0.6	0.6	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.6	0.6	0.6	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.2	0.2	0.2	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.4	0.4	0.4	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.4	0.4	0.4	ns
PCI33	PCI33	0.3	0.3	0.3	ns

1. General timing numbers based on LVC MOS 2.5, 12mA.
Timing v.F0.11

Pin Information Summary¹ (Cont.)

Pin Type		XP10		XP15			XP20		
		256 fpBGA	388 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA
Single Ended User I/O		188	244	188	268	300	188	268	340
Differential Pair User I/O ²		76	104	76	112	128	76	112	144
Configuration	Dedicated	11	11	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14	14	14
TAP		5	5	5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6	6	6
V _{CC}		8	14	8	14	28	8	14	28
V _{CCAUX}		4	4	4	4	12	4	4	12
V _{CCPLL}		2	2	2	2	2	2	2	2
V _{CCIO}	Bank0	2	5	2	5	4	2	5	4
	Bank1	2	5	2	5	4	2	5	4
	Bank2	2	4	2	4	4	2	4	4
	Bank3	2	4	2	4	4	2	4	4
	Bank4	2	5	2	5	4	2	5	4
	Bank5	2	5	2	5	4	2	5	4
	Bank6	2	4	2	4	4	2	4	4
	Bank7	2	4	2	4	4	2	4	4
GND		24	50	24	50	56	24	50	56
GND _{PLL}		2	2	2	2	2	2	2	2
NC		0	24	0	0	40	0	0	0
Single Ended/ Differential I/O per Bank ²	Bank0	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank1	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank2	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank3	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank4	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank5	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank6	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank7	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
V _{CCJ}		1	1	1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
44	GNDIO4	4	-	-
45	PB15A	4	T	PCLKT4_0
46	PB15B	4	C	PCLKC4_0
47	VCCIO4	4	-	-
48	PB19A	4	T	DQS
49	PB19B	4	C	VREF1_4
50	PB24A	4	-	VREF2_4
51	PR18B	3	C ³	-
52	GNDIO3	3	-	-
53	PR18A	3	T ³	-
54	PR15B	3	-	VREF1_3
55	PR14A	3	-	VREF2_3
56	PR13B	3	C	-
57	PR13A	3	T	-
58	VCCIO3	3	-	-
59	GNDP1	-	-	-
60	VCCP1	-	-	-
61	PR9B	2	C	PCLKC2_0
62	PR9A	2	T	PCLKT2_0
63	PR8B	2	C	RUM0_PLLC_IN_A
64	PR8A	2	T	RUM0_PLLT_IN_A
65	VCCIO2	2	-	-
66	PR6B	2	-	VREF1_2
67	PR5A	2	-	VREF2_2
68	GNDIO2	2	-	-
69	PR3B	2	C	RUM0_PLLC_FB_A
70	PR3A	2	T	RUM0_PLLT_FB_A
71	VCCAUX	-	-	-
72	TDO	-	-	-
73	VCCJ	-	-	-
74	TDI	-	-	-
75	TMS	-	-	-
76	TCK	-	-	-
77	VCC	-	-	-
78	PT24A	1	-	-
79	PT23A	1	-	D0
80	PT22B	1	-	D1
81	PT21A	1	-	D2
82	VCCIO1	1	-	-
83	PT20B	1	-	D3
84	GNDIO1	1	-	-
85	PT17A	1	-	D4
86	PT16A	1	-	D5
87	PT15B	1	-	D6

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
47	PB11A	5	T	DQS	PB14A	5	T	DQS
48	PB11B	5	C	-	PB14B	5	C	-
49	VCCIO5	5	-	-	VCCIO5	5	-	-
50	PB12A	5	T	-	PB15A	5	T	-
51	PB12B	5	C	-	PB15B	5	C	-
52	PB13A	5	T	-	PB16A	5	T	-
53	PB13B	5	C	-	PB16B	5	C	-
54	GND	-	-	-	GND	-	-	-
55	PB14A	4	T	-	PB17A	4	T	-
56	GNDIO4	4	-	-	GNDIO4	4	-	-
57	PB14B	4	C	-	PB17B	4	C	-
58	PB15A	4	T	PCLKT4_0	PB18A	4	T	PCLKT4_0
59	PB15B	4	C	PCLKC4_0	PB18B	4	C	PCLKC4_0
60	PB16A	4	T	-	PB19A	4	T	-
61	VCCIO4	4	-	-	VCCIO4	4	-	-
62	PB16B	4	C	-	PB19B	4	C	-
63	PB19A	4	T	DQS	PB22A	4	T	DQS
64	GNDIO4	4	-	-	GNDIO4	4	-	-
65	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
66	PB20A	4	T	-	PB23A	4	T	-
67	PB20B	4	C	-	PB23B	4	C	-
68	VCCIO4	4	-	-	VCCIO4	4	-	-
69	PB22A	4	-	-	PB25A	4	-	-
70	PB24A	4	T	VREF2_4	PB27A	4	T	VREF2_4
71	PB24B	4	C	-	PB27B	4	C	-
72	PB25A	4	-	-	PB28A	4	-	-
73	VCC	-	-	-	VCC	-	-	-
74	PR18B	3	C ³	-	PR26B	3	C ³	-
75	GNDIO3	3	-	-	GNDIO3	3	-	-
76	PR18A	3	T ³	-	PR26A	3	T ³	-
77	PR17B	3	C	-	PR25B	3	C	-
78	PR17A	3	T	-	PR25A	3	T	-
79	PR16B	3	C ³	-	PR24B	3	C ³	-
80	PR16A	3	T ³	DQS	PR24A	3	T ³	DQS
81	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
82	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
83	PR13B	3	C	-	PR21B	3	C ³	-
84	PR13A	3	T	-	PR21A	3	T ³	-
85	GND	-	-	-	GND	-	-	-
86	PR12A	3	-	-	PR20A	3	-	-
87	PR11B	3	C	-	PR19B	3	C ³	-
88	VCCIO3	3	-	-	VCCIO3	3	-	-
89	PR11A	3	T	-	PR19A	3	T ³	-
90	GNDP1	-	-	-	GNDP1	-	-	-
91	VCCP1	-	-	-	VCCP1	-	-	-
92	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L15	PR21B	3	C ³	-	PR28B	3	C ³	-
L14	PR21A	3	T ³	-	PR28A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L12	PR17B	3	C	-	PR26A	3	-	-
M16	PR20B	3	C	-	PR25B	3	C	RLM0_PLLC_IN_A
N16	PR20A	3	T	-	PR25A	3	T	RLM0_PLLT_IN_A
K14	PR19B	3	C ³	-	PR24B	3	C ³	-
K15	PR19A	3	T ³	-	PR24A	3	T ³	DQS
K12	PR17A	3	T	-	PR23B	3	-	-
K13	PR22A	3	-	VREF2_3	PR22A	3	-	VREF2_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
L16	PR18B	3	C ³	-	PR21B	3	C ³	-
K16	PR18A	3	T ³	-	PR21A	3	T ³	-
J15	PR16B	3	C ³	-	PR19B	3	C ³	-
J14	PR16A	3	T ³	-	PR19A	3	T ³	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR12B	2	C	PCLKC2_0	PR17B	2	C	PCLKC2_0
H16	PR12A	2	T	PCLKT2_0	PR17A	2	T	PCLKT2_0
H13	PR13B	2	C ³	-	PR16B	2	C ³	-
H12	PR13A	2	T ³	-	PR16A	2	T ³	DQS
H15	PR2B	2	C ³	-	PR15B	2	-	-
H14	PR6B	2	-	VREF1_2	PR14A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR11B	2	C ³	-	PR13B	2	C ³	-
G14	PR11A	2	T ³	-	PR13A	2	T ³	-
G16	PR8B	2	C	RUM0_PLLC_IN_A	PR12B	2	C	RUM0_PLLC_IN_A
F16	PR8A	2	T	RUM0_PLLT_IN_A	PR12A	2	T	RUM0_PLLT_IN_A
G13	PR2A	2	T ³	-	PR11B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR9B	2	C ³	-	PR8B	2	C	-
F13	PR9A	2	T ³	-	PR8A	2	T	-
B16	PR7B	2	C ³	-	PR7B	2	C ³	-
C16	PR7A	2	T ³	DQS	PR7A	2	T ³	DQS
F15	PR14A	2	-	-	PR6B	2	-	-
E15	PR5A	2	-	VREF2_2	PR5A	2	-	VREF2_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F14	PR4B	2	C ³	-	PR4B	2	C ³	-
E14	PR4A	2	T ³	-	PR4A	2	T ³	-
D15	PR3B	2	C	RUM0_PLLC_FB_A	PR3B	2	C	RUM0_PLLC_FB_A
C15	PR3A	2	T	RUM0_PLLT_FB_A	PR3A	2	T	RUM0_PLLT_FB_A

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L4	PL32A	6	-	-	PL36A	6	-	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K4	PL33A	6	T	-	PL37A	6	T	-
K5	PL33B	6	C	-	PL37B	6	C	-
N1	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
N2	PL36B	6	-	-	PL40B	6	-	-
P1	PL37A	6	T ³	DQS	PL41A	6	T ³	DQS
P2	PL37B	6	C ³	-	PL41B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L5	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
M6	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
M3	PL39A	6	T ³	-	PL43A	6	T ³	-
N3	PL39B	6	C ³	-	PL43B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
P4	SLEEPN ¹ /TOE ²	-	-	-	SLEEPN ¹ /TOE ²	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB11A	5	T	-	PB15A	5	T	-
N5	PB11B	5	C	-	PB15B	5	C	-
P5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R1	PB12B	5	C	-	PB16B	5	C	-
N6	PB13A	5	-	-	PB17A	5	-	-
M7	PB14B	5	-	-	PB18B	5	-	-
R2	PB15A	5	T	DQS	PB19A	5	T	DQS
T2	PB15B	5	C	-	PB19B	5	C	-
R3	PB16A	5	T	-	PB20A	5	T	-
T3	PB16B	5	C	-	PB20B	5	C	-
T4	PB17A	5	T	-	PB21A	5	T	-
R5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
N7	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
M8	PB18B	5	C	-	PB22B	5	C	-
T5	PB19A	5	T	-	PB23A	5	T	-
P6	PB19B	5	C	-	PB23B	5	C	-
T6	PB20A	5	T	-	PB24A	5	T	-
R6	PB20B	5	C	-	PB24B	5	C	-
P7	PB21A	5	-	-	PB25A	5	-	-
N8	PB22B	5	-	-	PB26B	5	-	-
R7	PB23A	5	T	DQS	PB27A	5	T	DQS

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
G7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
G10	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G9	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
H8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G13	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G14	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
J16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
K16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
N16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
P16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T13	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T14	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
R8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T10	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T9	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
N7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
P7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
R7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
H7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
J7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
K7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP "C" only.
2. Applies to LFXP "E" only.
3. Supports dedicated LVDS outputs.

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6E-3F256C	188	1.2V	-3	fpBGA	256	COM	5.8K
LFXP6E-4F256C	188	1.2V	-4	fpBGA	256	COM	5.8K
LFXP6E-5F256C	188	1.2V	-5	fpBGA	256	COM	5.8K
LFXP6E-3Q208C	142	1.2V	-3	PQFP	208	COM	5.8K
LFXP6E-4Q208C	142	1.2V	-4	PQFP	208	COM	5.8K
LFXP6E-5Q208C	142	1.2V	-5	PQFP	208	COM	5.8K
LFXP6E-3T144C	100	1.2V	-3	TQFP	144	COM	5.8K
LFXP6E-4T144C	100	1.2V	-4	TQFP	144	COM	5.8K
LFXP6E-5T144C	100	1.2V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3F388C	244	1.2V	-3	fpBGA	388	COM	9.7K
LFXP10E-4F388C	244	1.2V	-4	fpBGA	388	COM	9.7K
LFXP10E-5F388C	244	1.2V	-5	fpBGA	388	COM	9.7K
LFXP10E-3F256C	188	1.2V	-3	fpBGA	256	COM	9.7K
LFXP10E-4F256C	188	1.2V	-4	fpBGA	256	COM	9.7K
LFXP10E-5F256C	188	1.2V	-5	fpBGA	256	COM	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3F484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4F484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5F484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3F388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4F388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5F388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3F256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4F256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5F256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Industrial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10E-3FN388I	244	1.2V	-3	fpBGA	388	IND	9.7K
LFXP10E-4FN388I	244	1.2V	-4	fpBGA	388	IND	9.7K
LFXP10E-3FN256I	188	1.2V	-3	fpBGA	256	IND	9.7K
LFXP10E-4FN256I	188	1.2V	-4	fpBGA	256	IND	9.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484I	300	1.2V	-3	fpBGA	484	IND	15.5K
LFXP15E-4FN484I	300	1.2V	-4	fpBGA	484	IND	15.5K
LFXP15E-3FN388I	268	1.2V	-3	fpBGA	388	IND	15.5K
LFXP15E-4FN388I	268	1.2V	-4	fpBGA	388	IND	15.5K
LFXP15E-3FN256I	188	1.2V	-3	fpBGA	256	IND	15.5K
LFXP15E-4FN256I	188	1.2V	-4	fpBGA	256	IND	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484I	340	1.2V	-3	fpBGA	484	IND	19.7K
LFXP20E-4FN484I	340	1.2V	-4	fpBGA	484	IND	19.7K
LFXP20E-3FN388I	268	1.2V	-3	fpBGA	388	IND	19.7K
LFXP20E-4FN388I	268	1.2V	-4	fpBGA	388	IND	19.7K
LFXP20E-3FN256I	188	1.2V	-3	fpBGA	256	IND	19.7K
LFXP20E-4FN256I	188	1.2V	-4	fpBGA	256	IND	19.7K

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
	02.0	DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
		Ordering Information	Updated Logic Signal Connections Dual Function column.
			Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.